

# FQD6N40C / FQU6N40C

## N-Channel QFET MOSFET

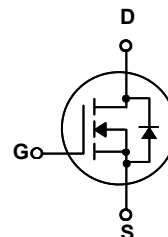
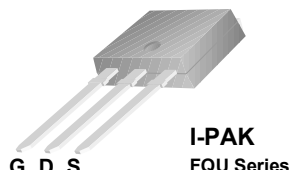
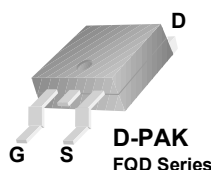
400 V, 4.5 A, 1.0  $\Omega$

### Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

### Features

- 4.5 A, 400 V,  $R_{DS(on)} = 1.0 \Omega$  (Max) @  $V_{GS} = 10$  V,  $I_D = 2.25$  A
- Low Gate Charge (Typ. 16 nC)
- Low  $C_{rss}$  (Typ. 15 pF)
- 100% Avalanche Tested



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQD6N40C / FQU6N40C	Unit
$V_{DSS}$	Drain-Source Voltage	400	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	4.5	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	2.7	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	18	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	270	mJ
$I_{AR}$	Avalanche Current (Note 1)	4.5	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	4.8	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_A = 25^\circ\text{C}$ )*	2.5	W
	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	48	W
	- Derate above $25^\circ\text{C}$	0.38	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	2.6	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient.*	--	50	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient.	--	110	$^\circ\text{C}/\text{W}$

\* When mounted on the minimum pad size recommended (PCB Mount)

**Electrical Characteristics** $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	400	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.54	--	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 320\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

**On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 2.25\text{ A}$	--	0.83	1	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 2.25\text{ A}$ (Note 4)	--	4.7	--	S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	480	625	pF
$C_{oss}$	Output Capacitance		--	80	105	pF
$C_{rss}$	Reverse Transfer Capacitance		--	15	20	pF

**Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 200\text{ V}, I_D = 6\text{ A},$ $R_G = 25\text{ }\Omega$  (Note 4, 5)	--	13	35	ns
$t_r$	Turn-On Rise Time		--	65	140	ns
$t_{d(off)}$	Turn-Off Delay Time		--	21	55	ns
$t_f$	Turn-Off Fall Time		--	38	85	ns
$Q_g$	Total Gate Charge	$V_{DS} = 320\text{ V}, I_D = 6\text{ A},$ $V_{GS} = 10\text{ V}$  (Note 4, 5)	--	16	20	nC
$Q_{gs}$	Gate-Source Charge		--	2.3	--	nC
$Q_{gd}$	Gate-Drain Charge		--	8.2	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	4.5	A	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	18	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 4.5 A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 6 A,	--	230	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs (Note 4)	--	1.7	--	μC

**Notes:**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 13.7\text{ mH}, I_{AS} = 6\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\text{ }\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 6\text{ A}, dI/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature

## Typical Characteristics

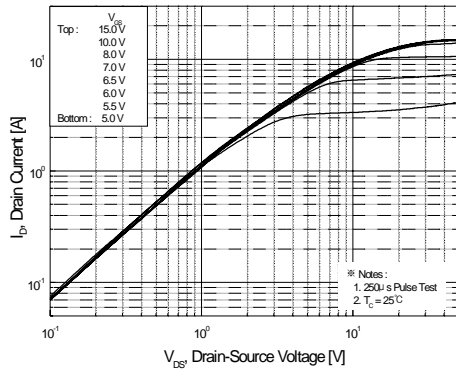


Figure 1. On-Region Characteristics

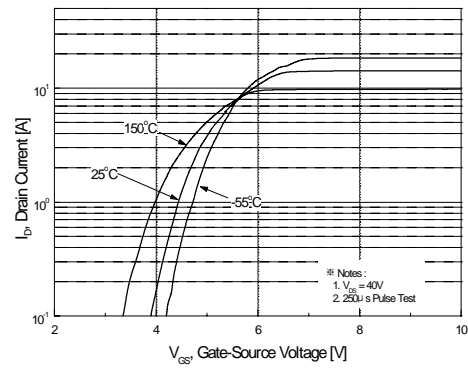


Figure 2. Transfer Characteristics

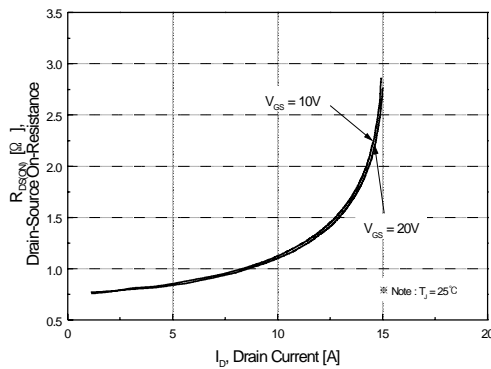


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

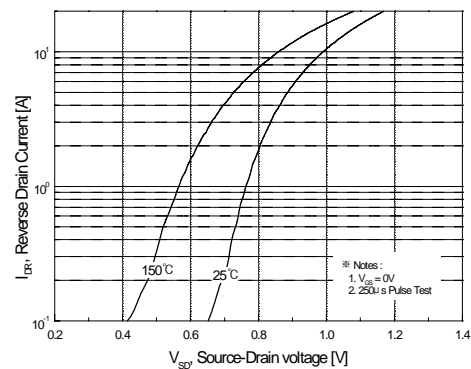


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

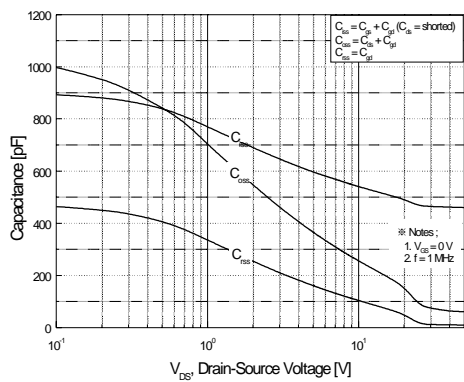


Figure 5. Capacitance Characteristics

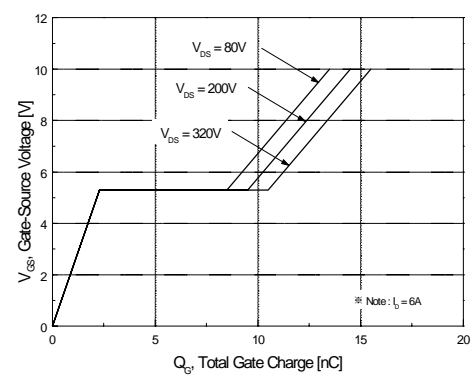
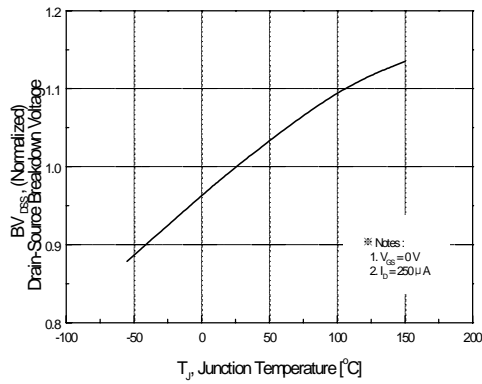
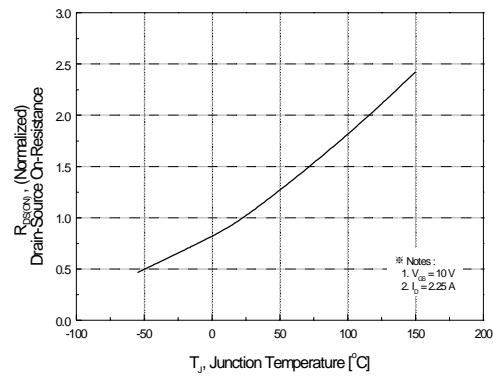


Figure 6. Gate Charge Characteristics

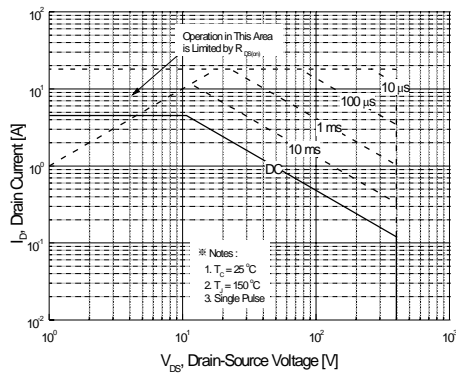
## Typical Characteristics (Continued)



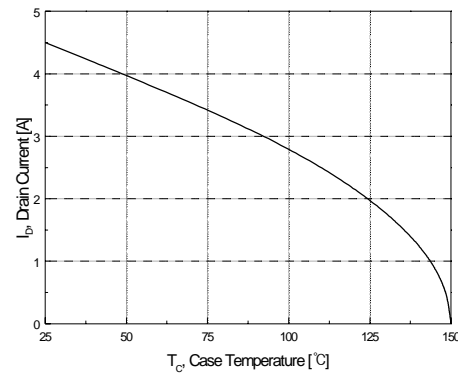
**Figure 7. Breakdown Voltage Variation vs Temperature**



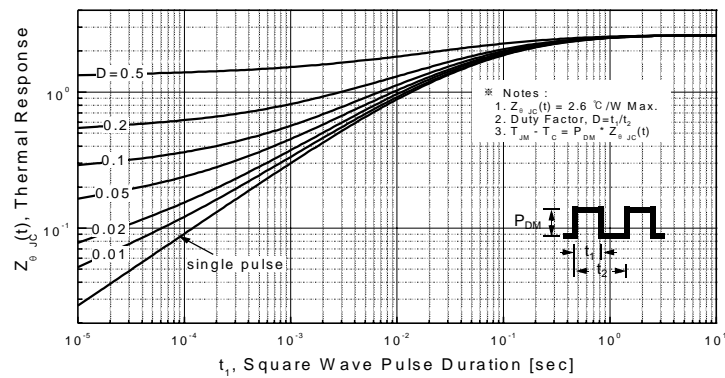
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9. Maximum Safe Operating Area**

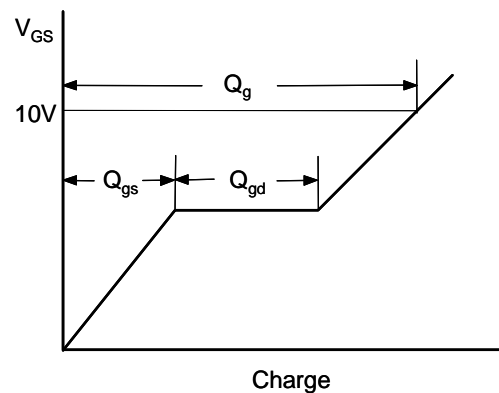
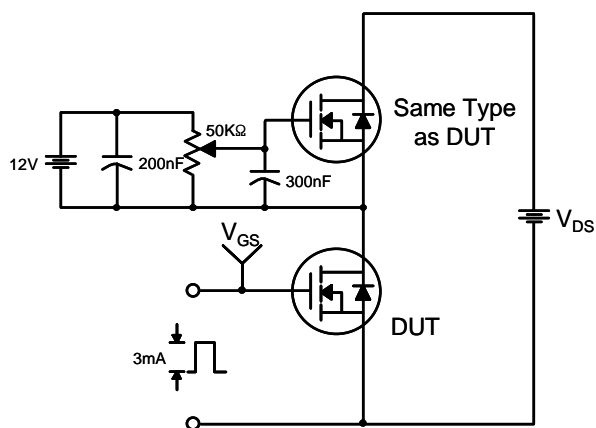


**Figure 10. Maximum Drain Current vs Case Temperature**

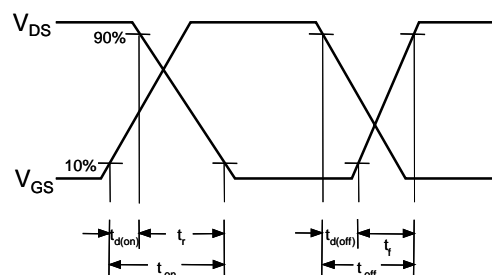
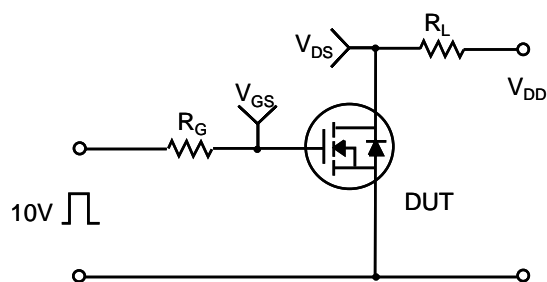


**Figure 11. Transient Thermal Response Curve**

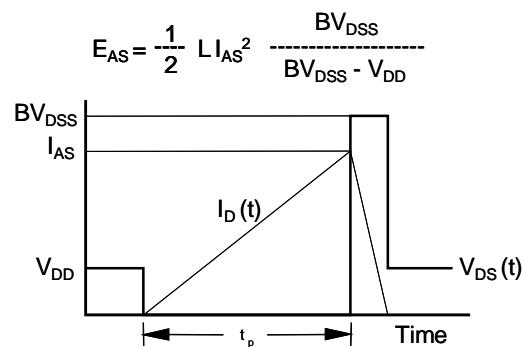
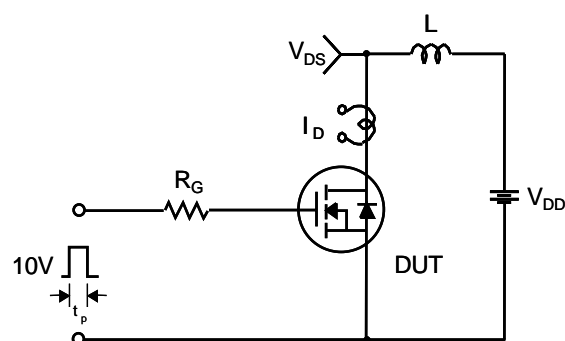
### Gate Charge Test Circuit & Waveform



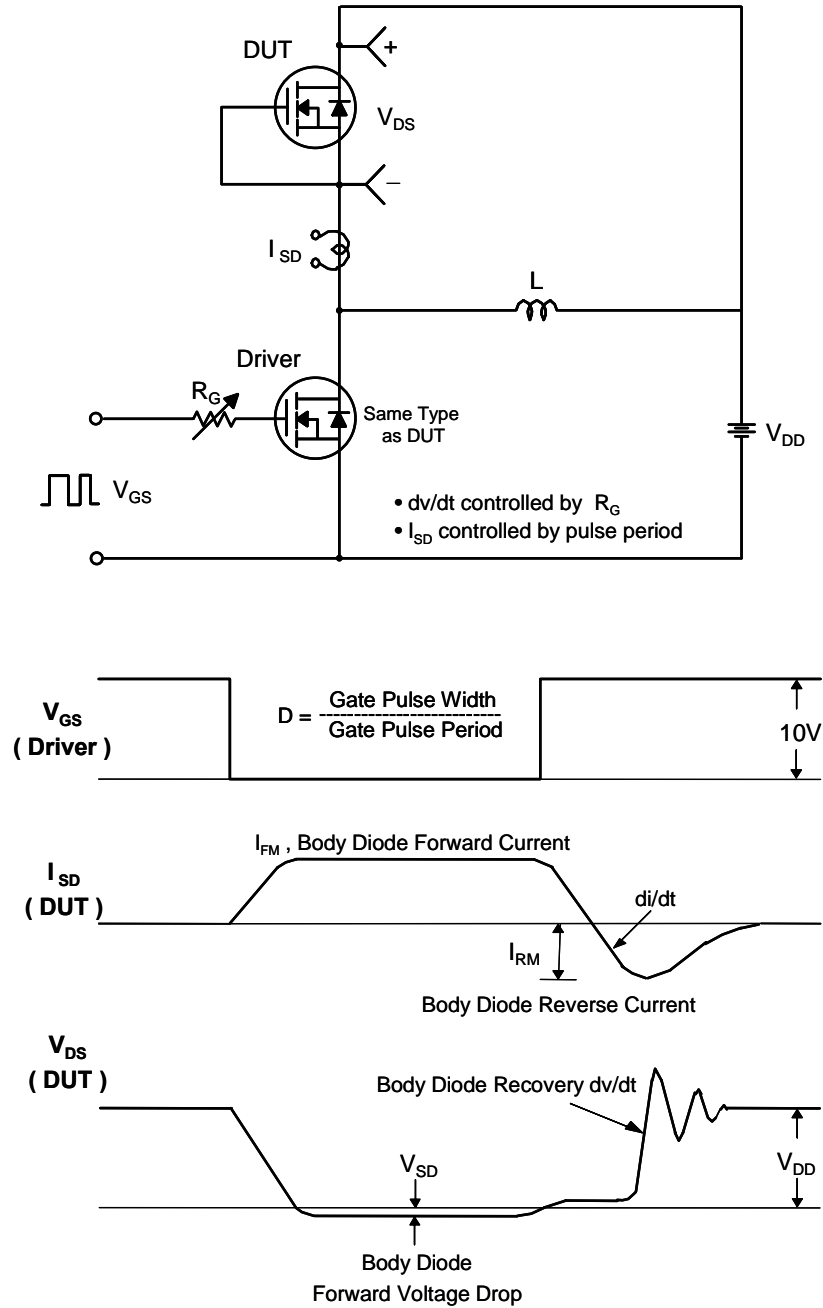
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching Test Circuit & Waveforms



# Peak Diode Recovery dv/dt Test Circuit & Waveforms





Technical drawing of a mechanical part, showing front, side, and top views with dimensions and tolerances.

**Front View Dimensions:**

- Overall width: 6.80 (tolerance 6.35)
- Inner width: 5.54 (tolerance 5.14)
- Top step width: 4
- Top step height: 1.27 (tolerance 0.50)
- Main body height: 6.30 (tolerance 5.90)
- Internal feature height: 1.52 (tolerance 0.70)
- Internal feature width: 2.28 (tolerance 1.60)
- Bottom section height: 9.65 (tolerance 8.90)
- Bottom section width: 1.14 (tolerance 0.76)
- Bottom section depth: 2.29
- Bottom section width (left): 0.88 (tolerance 0.64)
- Bottom section width (right): 0.60

**Side View Dimensions:**

- Overall height: 2.50 (tolerance 2.10)
- Top step height: 0.60 (tolerance 0.40)
- Bottom section height: 1.14 (tolerance 0.90)
- Bottom section width: 0.60 (tolerance 0.40)

**Top View Dimensions:**

- Overall width: 0.25 (tolerance 0.10)
- Overall height: 0.25 (tolerance 0.10)
- Overall width (right): 0.25 (tolerance 0.10)
- Overall height (right): 0.25 (tolerance 0.10)

**Annotations:**

- Feature A: Top step
- Feature B: Internal feature
- Feature C: Bottom section
- Feature D: Bottom section (left)
- Feature E: Bottom section (right)

**Material and Quantity:**




- Material: 3 PLCS

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